CLAIMS

[Claim 1]

A maleimide resin composition comprising

(A) one or more selected from a group consisting of a maleimide compound having one or more N-substituted maleimide groups and a derivative thereof, and

(B) a polymer having a hydrocarbon chain or a polyether chain in a main chain thereof, wherein

the component (A) contains

(A1) a maleimide compound having one or more N-substituted maleimide groups and a molecular weight of less than 600, and

(A2) a maleimide compound having one or more N-substituted maleimide groups and a molecular weight of 600 or more, and

the component (B) is (B1) a modified conjugated diene polymer obtained by modifying (b1) a conjugated diene polymer having a vinyl group in a side chain thereof with (b2) a maleimide compound having two or more N-substituted maleimide groups.

[Claim 2]

The maleimide resin composition according to claim 1, wherein the component (A1) is an aromatic bismaleimide compound.

[Claim 3]

The maleimide resin composition according to claim 1 or 2, wherein the component (A2) is a maleimide compound containing an alicyclic hydrocarbon group.

[Claim 4]

The maleimide resin composition according to claim 3, wherein the alicyclic hydrocarbon group is contained as part of an indane ring.

[Claim 5]

The maleimide resin composition according to any one of claims 1 to 4, wherein the component (B) is a polymer having a hydrocarbon chain in a main chain thereof.

[Claim 6]

The maleimide resin composition according to claim 5, wherein the component (B1) has, on a side chain thereof, a substituent obtained by reacting the vinyl group of the component (b1) with the N-substituted maleimide group of the component (b2).

[Claim 7]

The maleimide resin composition according to claim 5 or 6, wherein the component (b1) is polybutadiene having a 1,2-vinyl group.

[Claim 8]

The maleimide resin composition according to any one of claims 1 to 7, wherein a content ratio of the component (A) and the component (B) [(A)/(B)] is 0.3 to 3.0 on a mass basis.

[Claim 9]

A prepreg comprising the maleimide resin composition according to any one of claims 1 to 8 or a semi-cured product of the maleimide resin composition.

[Claim 10]

A laminated board comprising a cured product of the maleimide resin composition according to any one of claims 1 to 8 or a cured product of the prepreg according to claim 9, and a metal foil.

[Claim 11]

A resin film comprising the maleimide resin composition according to any one of claims 1 to 8 or a semi-cured product of the maleimide resin composition.

[Claim 12]

A printed wiring board comprising one or more selected from a group consisting of a cured product of the maleimide resin composition according to any one of claims 1 to 8, a cured product of the prepreg according to claim 9, and the laminated board according to claim 10.

[Claim 13]

A semiconductor package comprising the printed wiring board according to claim 12 and a semiconductor element.